

### **General Purpose Schottky Barrier Diode**

#### **General Description**

These Schottky barrier diodes are designed for high-speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conductions. Miniature surface mount package is excellent for hand-held and portable applications where space is limited.

#### **Features and Benefits**

- · Low forward drop voltage and low leakage current
- Very low switching time
- Full lead (Pb)-free device and RoHS compliant device
- Available in "Green" device

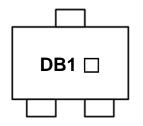
#### **Applications**

- · General purpose and high speed switching
- Protection circuit and voltage clamping

#### **Ordering Information**

Part Number	Marking Code	Package	Packaging
SDB3101F	DB1 🗌	SOT-23F	Tape & Reel

#### **Marking Information**



**DB1 = Specific Device Code** 

□ = Year & Week Code Marking

#### **Pinning Information**

Pin	Description	Simplified Outline	Graphic Symbol
1	Anode	3	
2	Not Connected		<b>*</b>
3	Cathode		





SOT-23F

### Absolute Maximum Ratings (T<sub>amb</sub>=25°C, Unless otherwise specified)

Characteristic	Symbol	Ratings	Unit
Peak reverse voltage	V <sub>RM</sub>	40	V
DC reverse voltage	V <sub>R</sub>	30	V
Repetitive peak forward current	I <sub>FRM</sub>	0.5	А
Forward current	I <sub>F</sub>	0.2	A
Non-repetitive peak forward surge current(t=10ms)	I <sub>FSM</sub>	2	А
Power dissipation <sup>1)</sup>	P <sub>D</sub>	150	mW

<sup>1)</sup> Device mounted on FR-4 board with recommended pad layout.

#### Thermal Characteristics (T<sub>amb</sub>=25°C, Unless otherwise specified)

Characteristic	Symbol	Ratings	Unit
Thermal resistance, junction to ambient 1)	R <sub>th(j-a)</sub>	833	°C/W
Operating junction temperature	Tj	150	°C
Storage temperature range	T <sub>stg</sub>	-55 ~ 150	°C

<sup>1)</sup> Device mounted on FR-4 board with recommended pad layout.

#### Electrical Characteristics (T<sub>amb</sub>=25°C, Unless otherwise specified)

Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Forward voltage 2)	V <sub>F(1)</sub>	I <sub>F</sub> =10mA	-	-	0.4	V
Torward voltage	V <sub>F(2)</sub>	I <sub>F</sub> =30mA	-	-	0.5	V
Reverse leakage current 3)	I <sub>R</sub>	V <sub>R</sub> =30V	-	-	1	μA
Total capacitance	C <sub>T</sub>	V <sub>R</sub> =1V, f=1MHz	-	-	10	pF
Reverse recovery time	t <sub>rr</sub>	$I_F = I_R = 10 \text{mA}, I_{R(REC)} = 1 \text{mA}$	-	-	5	ns

<sup>2)</sup> Pulse test:  $t_P \leq 380 \mu$ s, Duty cycle  $\leq 2\%$ 

<sup>3)</sup> Pulse test:  $t_P \le 5ms$ , Duty cycle  $\le 2\%$ 

### **Rating and Characteristic Curves**

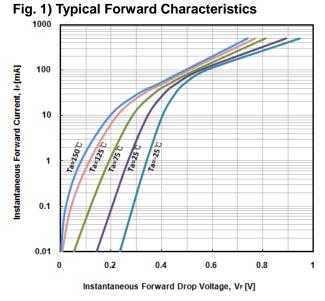
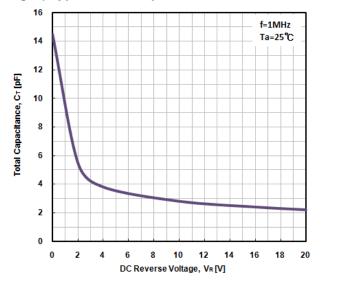
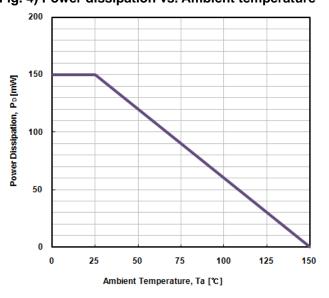


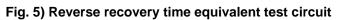
Fig. 3) Typical Total Capacitance Characteristics

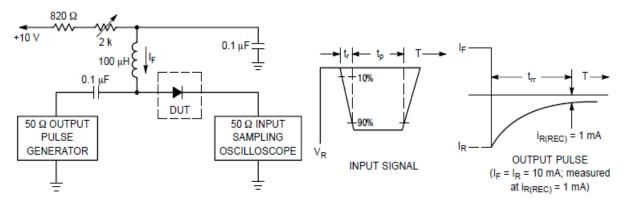


#### 1000 Ta=150°C Instantaneous Reverse Leakage Current, I<sub>R</sub> [uA] Ta=125°C 100 Ta=75℃ 10 1 Ta=25℃ 0.1 0.01 Ta=-25°C 0.001 0.0001 0 10 20 40 50 30 Instantaneous Reverse Voltage, V<sub>R</sub> [V]

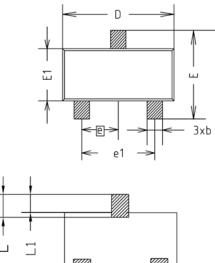
Fig. 4) Power dissipation vs. Ambient temperature

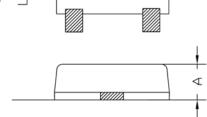


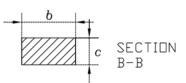


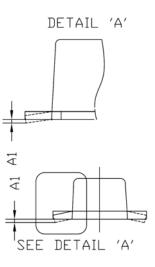


### Package Outline Dimensions



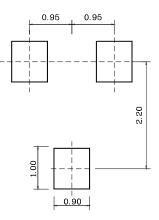






SYMBOL	١	NOTE		
STINDUL	MINIMUM	NOMINAL	MAXIMUM	NUIE
A	0.80	0.90	1.00	
A1	0.00	-	0.10	
b	0.35	0.40	0.45	
C	0.10	0.15	0.20	
D	2.80	2.90	3.00	
E	2.30	2.40	2.50	
E1	1.50	1.60	1.70	
e	0.95BSC			
e1	1.80	1.90	2.00	
L	0.48	0.58	0.68	
1	0.30	-	0.50	

#### **% Recommend PCB solder land (Unit : mm)**



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